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## Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

### **Details**

Product Status	Obsolete
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	73
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280c-4t100c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280c-4t100c</a>

June 2013

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## Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - Single chip, no external configuration memory required
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through JTAG port
  - Supports background programming of non-volatile memory
- **Sleep Mode**
  - Allows up to 100x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **High I/O to Logic Density**
  - 256 to 2280 LUT4s
  - 73 to 271 I/Os with extensive package options
  - Density migration supported
  - Lead free/RoHS compliant packaging
- **Embedded and Distributed Memory**
  - Up to 27.6 Kbits sysMEM™ Embedded Block RAM
  - Up to 7.7 Kbits distributed RAM
  - Dedicated FIFO control logic

**Table 1-1. MachXO Family Selection Guide**

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V <sub>CC</sub> Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
<b>Packages</b>				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

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The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

### Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

**Table 2-2. Slice Modes**

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

**Logic Mode:** In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

**Ripple Mode:** Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

**RAM Mode:** In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

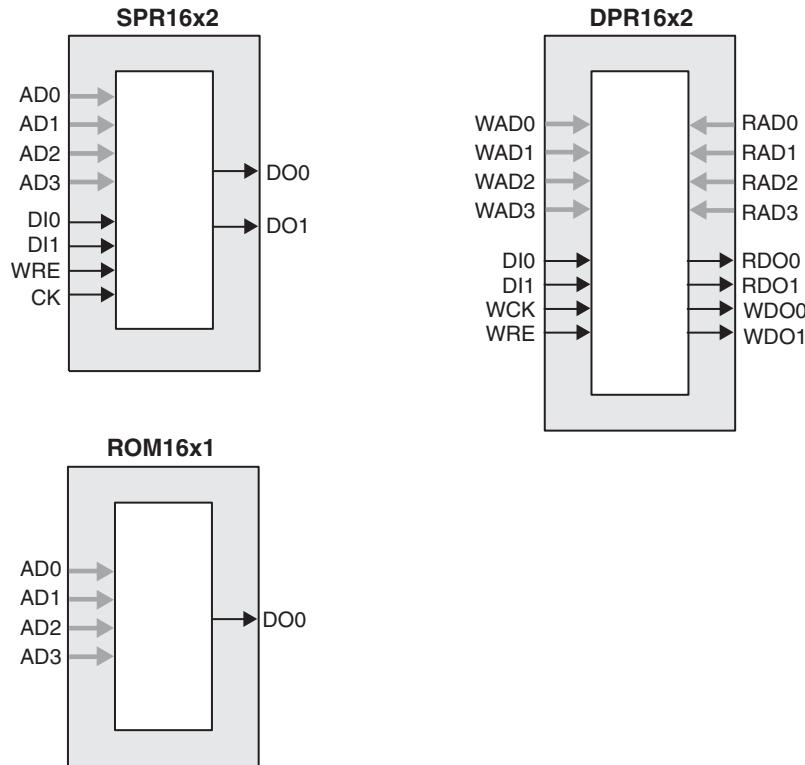
The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

**Table 2-3. Number of Slices Required For Implementing Distributed RAM**

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

**Figure 2-6. Distributed Memory Primitives**



**ROM Mode:** The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

#### PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

**Table 2-4. PFU Modes of Operation**

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

#### Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

## sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL\_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the  $t_{LOCK}$  parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

**Figure 2-10. PLL Diagram**

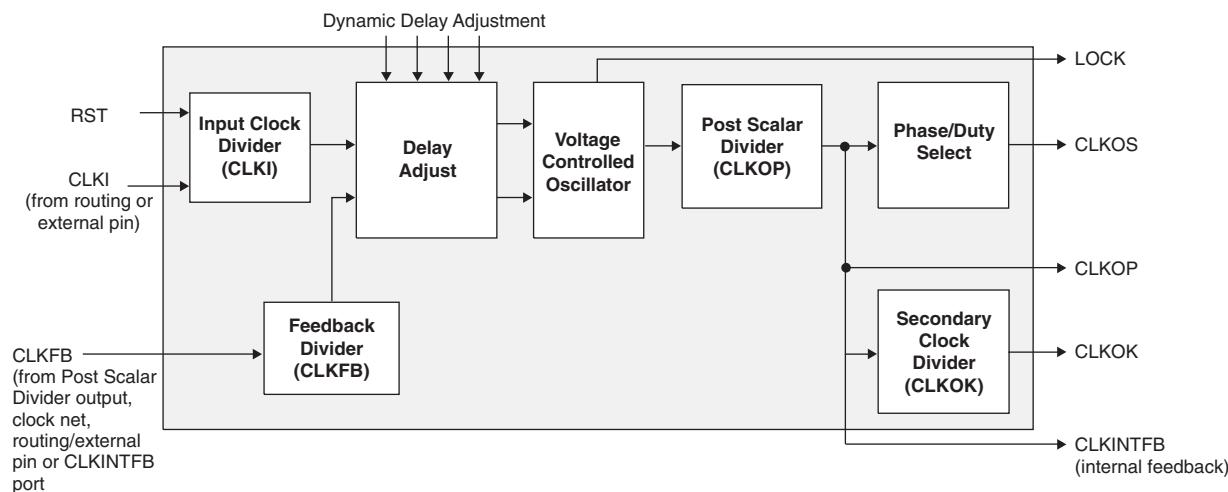
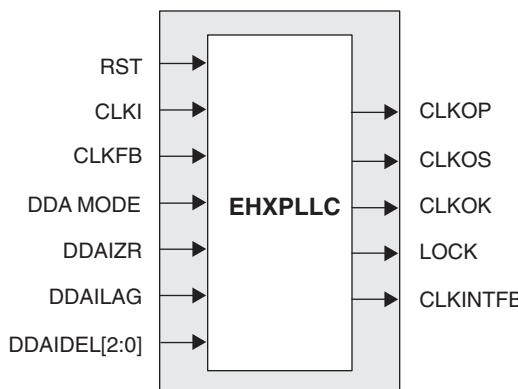


Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

**Figure 2-11. PLL Primitive**



**Table 2-5. PLL Signal Descriptions**

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

## sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

### sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

**Table 2-6. sysMEM Block Configurations**

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

**Table 2-8. I/O Support Device by Device**

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

**Table 2-9. Supported Input Standards**

Input Standard	VCCIO (Typ.)				
	3.3V	2.5V	1.8V	1.5V	1.2V
<b>Single Ended Interfaces</b>					
LVTTL	Yes	Yes	Yes	Yes	Yes
LVCMOS33	Yes	Yes	Yes	Yes	Yes
LVCMOS25	Yes	Yes	Yes	Yes	Yes
LVCMOS18			Yes		
LVCMOS15				Yes	
LVCMOS12	Yes	Yes	Yes	Yes	Yes
PCI <sup>1</sup>	Yes				
<b>Differential Interfaces</b>					
BLVDS <sup>2</sup> , LVDS <sup>2</sup> , LVPECL <sup>2</sup> , RSDS <sup>2</sup>	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.

2. MachXO1200 and MachXO2280 devices only.



# MachXO Family Data Sheet

## DC and Switching Characteristics

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### Absolute Maximum Ratings<sup>1, 2, 3</sup>

	LCMXO E (1.2V)	LCMXO C (1.8V/2.5V/3.3V)
Supply Voltage V <sub>CC</sub> .....	-0.5 to 1.32V .....	-0.5 to 3.75V .....
Supply Voltage V <sub>CCAUX</sub> .....	-0.5 to 3.75V .....	-0.5 to 3.75V .....
Output Supply Voltage V <sub>CCIO</sub> .....	-0.5 to 3.75V .....	-0.5 to 3.75V .....
I/O Tristate Voltage Applied <sup>4</sup> .....	-0.5 to 3.75V .....	-0.5 to 3.75V .....
Dedicated Input Voltage Applied <sup>4</sup> .....	-0.5 to 3.75V .....	-0.5 to 4.25V .....
Storage Temperature (ambient).....	-65 to 150°C .....	-65 to 150°C .....
Junction Temp. (T <sub>j</sub> ) .....	+125°C .....	+125°C .....

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V<sub>IHMAX</sub> + 2) volts is permitted for a duration of <20ns.

### Recommended Operating Conditions<sup>1</sup>

Symbol	Parameter	Min.	Max.	Units
V <sub>CC</sub>	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V <sub>CCAUX</sub> <sup>3</sup>	Auxiliary Supply Voltage	3.135	3.465	V
V <sub>CCIO</sub> <sup>2</sup>	I/O Driver Supply Voltage	1.14	3.465	V
t <sub>TJCOM</sub>	Junction Temperature Commercial Operation	0	+85	°C
t <sub>TJIND</sub>	Junction Temperature Industrial Operation	-40	100	°C
t <sub>TFLASHCOM</sub>	Junction Temperature, Flash Programming, Commercial	0	+85	°C
t <sub>TFLASHIND</sub>	Junction Temperature, Flash Programming, Industrial	-40	100	°C

1. Like power supplies must be tied together. For example, if V<sub>CCIO</sub> and V<sub>CC</sub> are both 2.5V, they must also be the same supply. 3.3V V<sub>CCIO</sub> and 1.2V V<sub>CCIO</sub> should be tied to V<sub>CCAUX</sub> or 1.2V V<sub>CC</sub> respectively.
2. See recommended voltages by I/O standard in subsequent table.
3. V<sub>CC</sub> must reach minimum V<sub>CC</sub> value before V<sub>CCAUX</sub> reaches 2.5V.

### MachXO Programming/Erase Specifications

Symbol	Parameter	Min.	Max.	Units
N <sub>PROGCYC</sub>	Flash Programming Cycles per t <sub>RETENTION</sub>		1,000	Cycles
	Flash Functional Programming Cycles		10,000	Cycles
t <sub>RETENTION</sub>	Data Retention at 125° Junction Temperature	10		Years

## Supply Current (Sleep Mode)<sup>1,2</sup>

Symbol	Parameter	Device	Typ. <sup>3</sup>	Max.	Units
$I_{CC}$	Core Power Supply	LCMxo256C	12	25	$\mu A$
		LCMxo640C	12	25	$\mu A$
		LCMxo1200C	12	25	$\mu A$
		LCMxo2280C	12	25	$\mu A$
$I_{CCAUX}$	Auxiliary Power Supply	LCMxo256C	1	15	$\mu A$
		LCMxo640C	1	25	$\mu A$
		LCMxo1200C	1	45	$\mu A$
		LCMxo2280C	1	85	$\mu A$
$I_{CCIO}$	Bank Power Supply <sup>4</sup>	All LCMxo 'C' Devices	2	30	$\mu A$

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3.  $T_A = 25^\circ C$ , power supplies at nominal voltage.

4. Per Bank.

## Supply Current (Standby)<sup>1, 2, 3, 4</sup>

### Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. <sup>5</sup>	Units
$I_{CC}$	Core Power Supply	LCMxo256C	7	mA
		LCMxo640C	9	mA
		LCMxo1200C	14	mA
		LCMxo2280C	20	mA
		LCMxo256E	4	mA
		LCMxo640E	6	mA
		LCMxo1200E	10	mA
		LCMxo2280E	12	mA
$I_{CCAUX}$	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMxo256E/C	5	mA
		LCMxo640E/C	7	mA
		LCMxo1200E/C	12	mA
		LCMxo2280E/C	13	mA
$I_{CCIO}$	Bank Power Supply <sup>6</sup>	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at  $V_{CCIO}$  or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5.  $T_J = 25^\circ C$ , power supplies at nominal voltage.

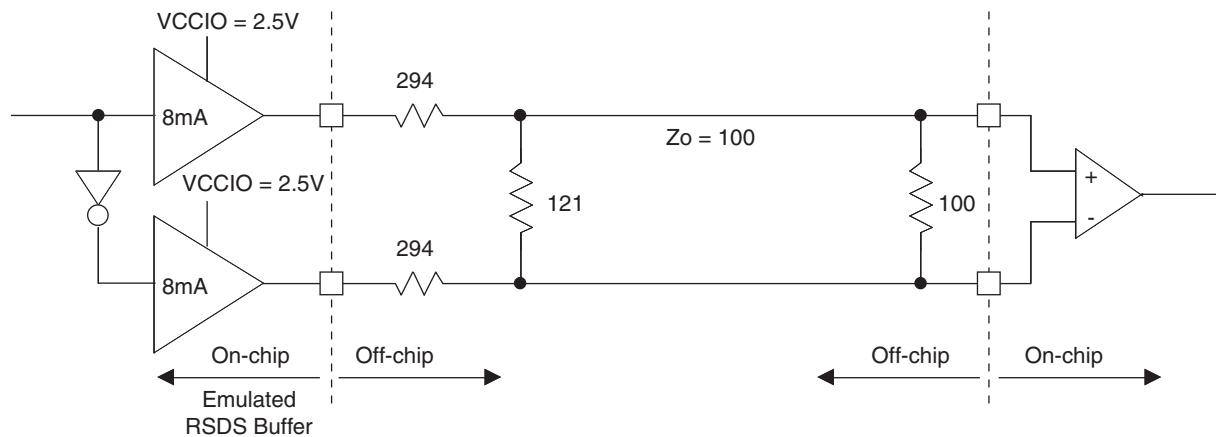
6. Per Bank.  $V_{CCIO} = 2.5V$ . Does not include pull-up/pull-down.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

## RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

**Figure 3-4. RSDS (Reduced Swing Differential Standard)**



**Table 3-4. RSDS DC Conditions**

Parameter	Description	Typical	Units
$Z_{OUT}$	Output impedance	20	Ohms
$R_S$	Driver series resistor	294	Ohms
$R_P$	Driver parallel resistor	121	Ohms
$R_T$	Receiver termination	100	Ohms
$V_{OH}$	Output high voltage	1.35	V
$V_{OL}$	Output low voltage	1.15	V
$V_{OD}$	Output differential voltage	0.20	V
$V_{CM}$	Output common mode voltage	1.25	V
$Z_{BACK}$	Back impedance	101.5	Ohms
$I_{DC}$	DC output current	3.66	mA

**LCMxo256 and LCMxo640 Logic Signal Connections: 100 TQFP**

Pin Number	LCMxo256				LCMxo640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	1		T	PL2A	3		T
2	PL2B	1		C	PL2C	3		T
3	PL3A	1		T	PL2B	3		C
4	PL3B	1		C	PL2D	3		C
5	PL3C	1		T	PL3A	3		T
6	PL3D	1		C	PL3B	3		C
7	PL4A	1		T	PL3C	3		T
8	PL4B	1		C	PL3D	3		C
9	PL5A	1		T	PL4A	3		
10	VCCIO1	1			VCCIO3	3		
11	PL5B	1		C	PL4C	3		T
12	GNDIO1	1			GNDIO3	3		
13	PL5C	1		T	PL4D	3		C
14	PL5D	1	GSRN	C	PL5B	3	GSRN	
15	PL6A	1		T	PL7B	3		
16	PL6B	1	TSALL	C	PL8C	3	TSALL	T
17	PL7A	1		T	PL8D	3		C
18	PL7B	1		C	PL9A	3		
19	PL7C	1		T	PL9C	3		
20	PL7D	1		C	PL10A	3		
21	PL8A	1		T	PL10C	3		
22	PL8B	1		C	PL11A	3		
23	PL9A	1		T	PL11C	3		
24	VCCIO1	1			VCCIO3	3		
25	GNDIO1	1			GNDIO3	3		
26	TMS	1	TMS		TMS	2	TMS	
27	PL9B	1		C	PB2C	2		
28	TCK	1	TCK		TCK	2	TCK	
29	PB2A	1		T	VCCIO2	2		
30	PB2B	1		C	GNDIO2	2		
31	TDO	1	TDO		TDO	2	TDO	
32	PB2C	1		T	PB4C	2		
33	TDI	1	TDI		TDI	2	TDI	
34	PB2D	1		C	PB4E	2		
35	VCC	-			VCC	-		
36	PB3A	1	PCLK1_1**	T	PB5B	2	PCLK2_1**	
37	PB3B	1		C	PB5D	2		
38	PB3C	1	PCLK1_0**	T	PB6B	2	PCLK2_0**	
39	PB3D	1		C	PB6C	2		
40	GND	-			GND	-		
41	VCCIO1	1			VCCIO2	2		
42	GNDIO1	1			GNDIO2	2		

**LCMxo1200 and LCMxo2280 Logic Signal Connections: 100 TQFP (Cont.)**

Pin Number	LCMxo1200				LCMxo2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
82	PT9A	1			PT12C	1		T
83	GND	-			GND	-		
84	PT8B	1		C	PT11B	1		C
85	PT8A	1		T	PT11A	1		T
86	PT7D	1	PCLK1_1****		PT10B	1	PCLK1_1****	
87	PT6F	0	PCLK0_0****		PT9B	1	PCLK1_0****	
88	PT6D	0		C	PT8F	0		C
89	PT6C	0		T	PT8E	0		T
90	VCCAUX	-			VCCAUX	-		
91	VCC	-			VCC	-		
92	PT5B	0			PT6D	0		
93	PT4B	0			PT6F	0		
94	VCCIO0	0			VCCIO0	0		
95	PT3D	0		C	PT4B	0		C
96	PT3C	0		T	PT4A	0		T
97	PT3B	0			PT3B	0		
98	PT2B	0		C	PT2B	0		C
99	PT2A	0		T	PT2A	0		T
100**	GNDIO0 GNDIO7	-			GNDIO0 GNDIO7	-		

\*Supports true LVDS outputs.

\*\*Double bonded to the pin.

\*\*\*NC for "E" devices.

\*\*\*\*Primary clock inputs are single-ended.

**LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)**

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		T	B4	PT3B	0		C
A3	PT2F	0		C	A3	PT3A	0		T
B3	PT2E	0		T	B3	PT2F	0		C
A2	PT2D	0		C	A2	PT2E	0		T
C3	PT2C	0		T	C3	PT2B	0		C
A1	PT2B	0		C	A1	PT2C	0		
B2	PT2A	0		T	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

\*NC for "E" devices.

\*\*Primary clock inputs are single-ended.

**LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections:  
 132 csBGA (Cont.)**

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

\*Supports true LVDS outputs.

\*\*NC for "E" devices.

\*\*\*Primary clock inputs are single-ended.

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640				LCMxo1200				LCMxo2280					
Ball Number	Ball Function	Bank	Dual Function	Ball Number	Ball Function	Bank	Dual Function	Ball Number	Ball Function	Bank	Dual Function		
J4	PL8A	3	T	J4	PL13A	6	T*	J4	PL16A	6	T*		
J5	PL8B	3	C	J5	PL13B	6	C*	J5	PL16B	6	C*		
R1	PL11A	3	T	R1	PL13C	6	T	R1	PL16C	6	T		
R2	PL11B	3	C	R2	PL13D	6	C	R2	PL16D	6	C		
-	-	-	-	-	-	-	-	GND	GND	-	-		
K5	NC			K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	
K4	NC			K4	PL14B	6	LLM0_PLLC_FB_A	C*	K4	PL17B	6	LLM0_PLLC_FB_A	
L5	PL10C	3	T	L5	PL14C	6	T	L5	PL17C	6	T		
L4	PL10D	3	C	L4	PL14D	6	C	L4	PL17D	6	C		
M5	NC			M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	
M4	NC			M4	PL15B	6	LLM0_PLLC_IN_A	C*	M4	PL18B	6	LLM0_PLLC_IN_A	
N4	PL11C	3	T	N4	PL16A	6	T	N4	PL19A	6	T		
N3	PL11D	3	C	N3	PL16B	6	C	N3	PL19B	6	C		
VCCIO3	VCCIO3	3		VCCIO6	VCCIO6	6		VCCIO6	VCCIO6	6			
GND	GNDIO3	3		GND	GNDIO6	6		GND	GNDIO6	6			
GND	GNDIO2	2		GND	GNDIO5	5		GND	GNDIO5	5			
VCCIO2	VCCIO2	2		VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
P4	TMS	2	TMS	P4	TMS	5	TMS	P4	TMS	5	TMS		
P2	NC			P2	PB2A	5	T	P2	PB2A	5	T		
P3	NC			P3	PB2B	5	C	P3	PB2B	5	C		
N5	NC			N5	PB2C	5	T	N5	PB2C	5	T		
R3	TCK	2	TCK	R3	TCK	5	TCK	R3	TCK	5	TCK		
N6	NC			N6	PB2D	5	C	N6	PB2D	5	C		
T2	PB2A	2	T	T2	PB3A	5	T	T2	PB3A	5	T		
T3	PB2B	2	C	T3	PB3B	5	C	T3	PB3B	5	C		
R4	PB2C	2	T	R4	PB3C	5	T	R4	PB3C	5	T		
R5	PB2D	2	C	R5	PB3D	5	C	R5	PB3D	5	C		
P5	PB3A	2	T	P5	PB4A	5	T	P5	PB4A	5	T		
P6	PB3B	2	C	P6	PB4B	5	C	P6	PB4B	5	C		
T5	PB3C	2	T	T5	PB4C	5	T	T5	PB4C	5	T		
M6	TDO	2	TDO	M6	TDO	5	TDO	M6	TDO	5	TDO		
T4	PB3D	2	C	T4	PB4D	5	C	T4	PB4D	5	C		
R6	PB4A	2	T	R6	PB5A	5	T	R6	PB5A	5	T		
GND	GNDIO2	2		GND	GNDIO5	5		GND	GNDIO5	5			
VCCIO2	VCCIO2	2		VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
T6	PB4B	2	C	T6	PB5B	5	C	T6	PB5B	5	C		
N7	TDI	2	TDI	N7	TDI	5	TDI	N7	TDI	5	TDI		
T8	PB4C	2	T	T8	PB5C	5	T	T8	PB6A	5	T		
T7	PB4D	2	C	T7	PB5D	5	C	T7	PB6B	5	C		
M7	NC			M7	PB6A	5	T	M7	PB7C	5	T		
M8	NC			M8	PB6B	5	C	M8	PB7D	5	C		
T9	VCCAUX	-		T9	VCCAUX	-		T9	VCCAUX	-			
R7	PB4E	2	T	R7	PB6C	5	T	R7	PB8C	5	T		
R8	PB4F	2	C	R8	PB6D	5	C	R8	PB8D	5	C		
-	-			VCCIO5	VCCIO5	5		VCCIO5	VCCIO5	5			
-	-			GND	GNDIO5	5		GND	GNDIO5	5			
P7	PB5C	2	T	P7	PB6E	5	T	P7	PB9A	4	T		
P8	PB5D	2	C	P8	PB6F	5	C	P8	PB9B	4	C		
N8	PB5A	2	T	N8	PB7A	4	T	N8	PB10E	4	T		
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***
P10	PB7B	2	C	P10	PB7D	4	C	P10	PB10D	4	C		
P9	PB7A	2	T	P9	PB7C	4	T	P9	PB10C	4	T		
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:  
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR8C	1		T	J13	PR11A	3			J13	PR14A	3		T*
GND	GND	-			GND	GND	-			GND	GND	-		
K14	PR8B	1		C	K14	PR10D	3			K14	PR13D	3		C
J14	PR8A	1		T	J14	PR10C	3			J14	PR13C	3		T
K15	PR7D	1		C	K15	PR10B	3			K15	PR13B	3		C*
J15	PR7C	1		T	J15	PR10A	3			J15	PR13A	3		T*
-	-				GND	GNDIO3	3			GND	GNDIO3	3		
-	-				VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
K12	NC				K12	PR9D	3			K12	PR11D	3		C
J12	NC				J12	PR9C	3			J12	PR11C	3		T
J16	PR7B	1		C	J16	PR9B	3			J16	PR11B	3		C*
H16	PR7A	1		T	H16	PR9A	3			H16	PR11A	3		T*
H15	PR6B	1		C	H15	PR8D	2			H15	PR10D	2		C
G15	PR6A	1		T	G15	PR8C	2			G15	PR10C	2		T
H14	PR5D	1		C	H14	PR8B	2			H14	PR10B	2		C*
G14	PR5C	1		T	G14	PR8A	2			G14	PR10A	2		T*
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
H13	PR6D	1		C	H13	PR7D	2			H13	PR9D	2		C
H12	PR6C	1		T	H12	PR7C	2			H12	PR9C	2		T
G13	PR4D	1		C	G13	PR7B	2			G13	PR9B	2		C*
G12	PR4C	1		T	G12	PR7A	2			G12	PR9A	2		T*
G16	PR5B	1		C	G16	PR6D	2			G16	PR7D	2		C
F16	PR5A	1		T	F16	PR6C	2			F16	PR7C	2		T
F15	PR4B	1		C	F15	PR6B	2			F15	PR7B	2		C*
E15	PR4A	1		T	E15	PR6A	2			E15	PR7A	2		T*
E16	PR3B	1		C	E16	PR5D	2			E16	PR6D	2		C
D16	PR3A	1		T	D16	PR5C	2			D16	PR6C	2		T
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
D15	PR2D	1		C	D15	PR5B	2			D15	PR6B	2		C*
C15	PR2C	1		T	C15	PR5A	2			C15	PR6A	2		T*
C16	PR2B	1		C	C16	PR4D	2			C16	PR5D	2		C
B16	PR2A	1		T	B16	PR4C	2			B16	PR5C	2		T
F14	PR3D	1		C	F14	PR4B	2			F14	PR5B	2		C*
E14	PR3C	1		T	E14	PR4A	2			E14	PR5A	2		T*
-	-	-			-	-	-			GND	GND	-		
F12	NC				F12	PR3D	2			F12	PR4D	2		C
F13	NC				F13	PR3C	2			F13	PR4C	2		T
E12	NC				E12	PR3B	2			E12	PR4B	2		C*
E13	NC				E13	PR3A	2			E13	PR4A	2		T*
D13	NC				D13	PR2B	2			D13	PR3B	2		C*
D14	NC				D14	PR2A	2			D14	PR3A	2		T*
VCCIO0	VCCIO0	0			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO0	0			GND	GNDIO2	2			GND	GNDIO2	2		
GND	GNDIO0	0			GND	GNDIO1	1			GND	GNDIO1	1		
VCCIO0	VCCIO0	0			VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
B15	NC				B15	PT11D	1			B15	PT16D	1		C
A15	NC				A15	PT11C	1			A15	PT16C	1		T
C14	NC				C14	PT11B	1			C14	PT16B	1		C
B14	NC				B14	PT11A	1			B14	PT16A	1		T
C13	PT9F	0		C	C13	PT10F	1			C13	PT15D	1		C
B13	PT9E	0		T	B13	PT10E	1			B13	PT15C	1		T

**LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)**

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

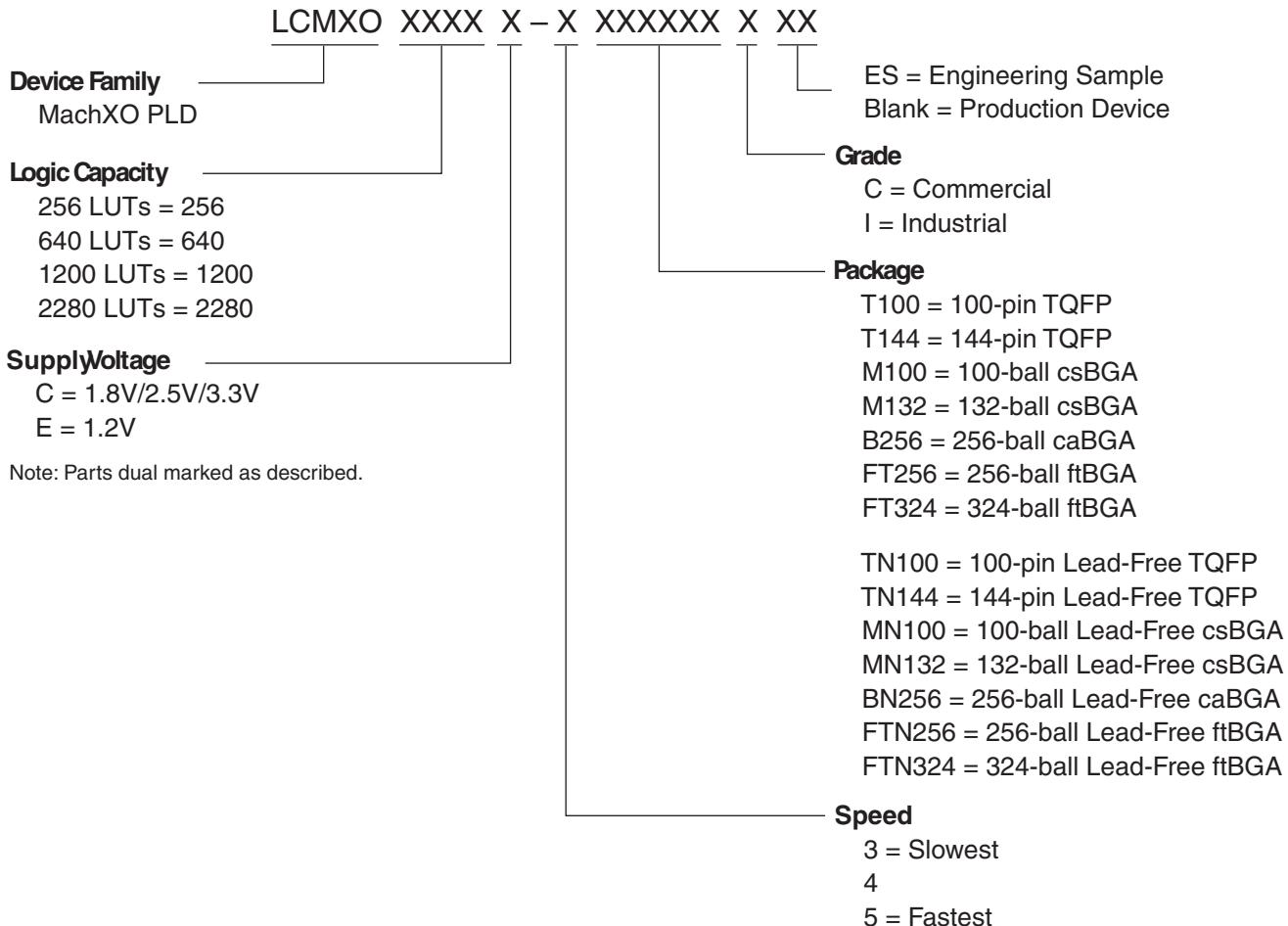
# MachXO Family Data Sheet

## Ordering Information

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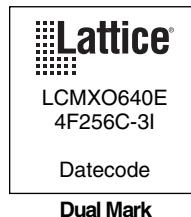
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### Part Number Description



### Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device.  
For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade.  
The slowest commercial speed grade does not have industrial markings.  
The markings appears as follows:



## Conventional Packaging

### Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256C-3T100I	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	IND
LCMxo256C-4T100I	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	IND
LCMxo256C-3M100I	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	IND
LCMxo256C-4M100I	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640C-3T100I	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	IND
LCMxo640C-4T100I	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	IND
LCMxo640C-3M100I	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	IND
LCMxo640C-4M100I	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	IND
LCMxo640C-3T144I	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo640C-4T144I	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo640C-3M132I	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo640C-4M132I	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo640C-3B256I	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	IND
LCMxo640C-4B256I	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	IND
LCMxo640C-3FT256I	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	IND
LCMxo640C-4FT256I	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200C-3T100I	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo1200C-4T100I	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo1200C-3T144I	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo1200C-4T144I	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo1200C-3M132I	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo1200C-4M132I	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo1200C-3B256I	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo1200C-4B256I	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo1200C-3FT256I	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo1200C-4FT256I	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3T100I	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMxo2280C-4T100I	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMxo2280C-3T144I	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMxo2280C-4T144I	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMxo2280C-3M132I	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMxo2280C-4M132I	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMxo2280C-3B256I	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMxo2280C-4B256I	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMxo2280C-3FT256I	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMxo2280C-4FT256I	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND
LCMxo2280C-3FT324I	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	IND
LCMxo2280C-4FT324I	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	IND



# MachXO Family Data Sheet

## Supplemental Information

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### For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, [MachXO sysIO Usage Guide](#)
- TN1089, [MachXO sysCLOCK Design and Usage Guide](#)
- TN1092, [Memory Usage Guide for MachXO Devices](#)
- TN1090, [Power Estimation and Management for MachXO Devices](#)
- TN1086, [MachXO JTAG Programming and Configuration User's Guide](#)
- TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#)
- TN1097, [MachXO Density Migration](#)
- AN8066, [Boundary Scan Testability with Lattice sysIO Capability](#)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTI, LVCMOS): [www.jedec.org](#)
- PCI: [www.pcisig.com](#)